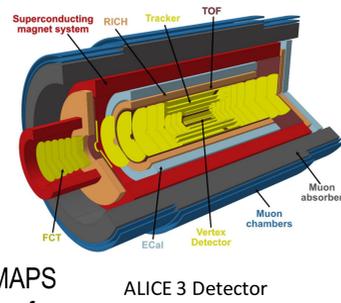


Research context and motivation

- **ALICE Experiment** is studying the properties of strongly interacting matter at **CERN**
- **ALICE 3 upgrade (2035)**: The new detector concept includes 2 new **Times of Flight (ToF)** layers for **PID**
 - Target : **20 ps** time resolution



ALICE 3 Detector

- **Fully Depleted Monolithic Active Pixel Sensors - FDMAPS**
 - Sensor and readout electronics in the same silicon wafer
 - Full depletion of the substrate allows to collect the charge mainly by **drift**

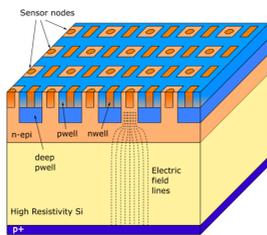
Compared to hybrid silicon detectors:

- Strong reduction in the material budget and costs
- Cheaper and simpler assembly

Still, a 20 ps time resolution far from the present technologies

ARCADIA, INFN project, as a first testbench :

- n-on-n sensor concept
- Deep p-well for CMOS electronics, 110 nm technology
- p+ boron doped backside layer, V_{back} negative for starting full depletion

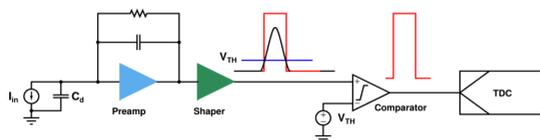


ARCADIA Sensors Scheme

Addressed research questions/problems

$$\sigma_t^2 = \sigma_{LandauNoise}^2 + \sigma_{Distortion}^2 + \sigma_{Jitter}^2 + \sigma_{TimeWalk}^2 + \sigma_{TDC}^2 + \sigma_{ck}^2$$

- ToF System key building blocks:
 - Sensor
 - Very front-end electronics
 - TDC, ck management system and readout electronics



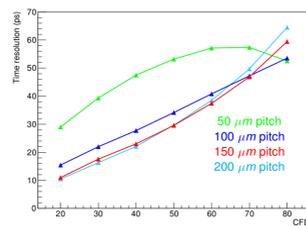
- Up to now, the best time resolution achieved is > 100 ps
The resolution limit is at the **sensor front-end interplay**

Sensor:

- Landau Noise – Fundamental limit
- Distortion – Uniform and fast collection of the charge

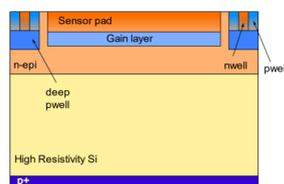
Front-end:

- Jitter – Noise and GBW optimization
- Time Walk – Correction techniques (ToT, Amplitude, CFD)



50 μm thick sensor resolution
C. Ferrero, G. Andriani

- ARCADIA pixel **sensor simulations** show:
 - Better time resolution for larger pixel pitches (electrodes) **< 20 ps at a pixel pitch > 150 μm**
 - Thinner sensors show better results, but less charge collected - higher electronics jitter !



L. Pancheri

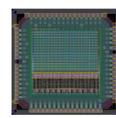
- An additional **Low Gain** layer implant can **increase** the **SNR**
 - A p doped gain layer can be added under the n electrode with minimal modification to the process
- Drawback:
- sensor top biased at HV (40 V)
 - Capacitive coupling with the 1.2 V CMOS electronics

Novel contributions

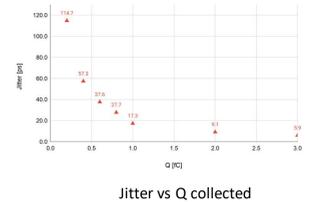
- This work is focused on the design of Fully Depleted CMOS sensors for fast timing applications in particle physics experiments
 - ARCADIA process FDMAPS prototype has been produced
 - A second different prototype implements a gain layer
- MAPS optimized for ps time resolution applications do not exist yet
- 20 ps resolution CMOS sensors will comply with the requirements dictated by ALICE 3 with the advantage of a strong reduction in the material budget and costs compared to hybrid solutions

Adopted methodologies

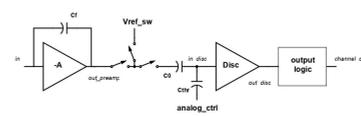
- 2 Prototypes have been designed and simulated with CAD simulation tools:



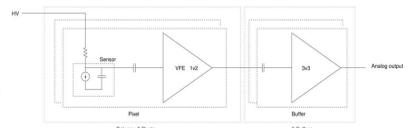
- **HERMES**
 - 2 x 2 mm²
 - 50 μm pitch pixels
 - Preamplifier + Discriminator (ToT)
 - $\sigma_{t-sensor} = 30/40$ ps , $\sigma_{t-fe} = 80$ ps
 - **Silicon now available**



Jitter vs Q collected

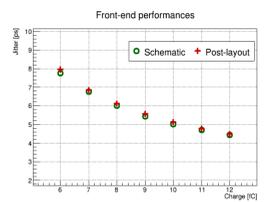


Channels block schemes

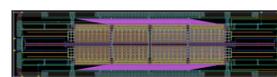


- **Monolithic CMOS Avalanche Detector prototype**

- 16.4 x 4.4
- Sensor gain between 10 and 20
- 250 x 100 μm² pixels
- Preamplifier, analog output
- $\sigma_{t-sensor} = 20$ ps , $\sigma_{jitter} < 10$ ps
- **Silicon available in December 2022**

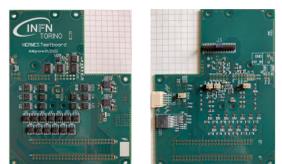


Jitter vs Q collected



Future work

- HERMES is ready to be tested
 - Testboard produced at INFN
- The prototype with gain will be available in December 2022
 - Ongoing activities for the production of the testboard
- 2023 Test Campaign is ready to start



HERMES PCB - M. Mignone

Submitted and published works

- S.Durando, "Ultra-Low Power Discrete-Time Readout for CMOS Radiation Sensors", Virtual IEEE Nuclear science symposium and medical imaging conference, Tokyo, 2021
- F.Camesecchi et al., "Direct detection of charged particles with SiPMs", IOP Journal of Instrumentation, vol. 17, no. 06, 2022, pp. P06007
- F.Camesecchi et al., "Beam test results of 25 μm and 35 μm thick FBK UFSD", Arxiv, 2022

List of attended classes

- 01TSGKG, The Monte Carlo Method, 29/10/2021, 40
- External Courses :
- Barcelona Technoweeek, 19/4/2021, 34
- Integrated Circuits for Detector Signal Processing and Radiation Hardened Design, 16/10/2021, 5
- XXX Giornate di Studio sui Rivelatori, 13/6/2022, 35.07
- Low Power Analog IC Design - Mead Education, 29/8/2022, 30